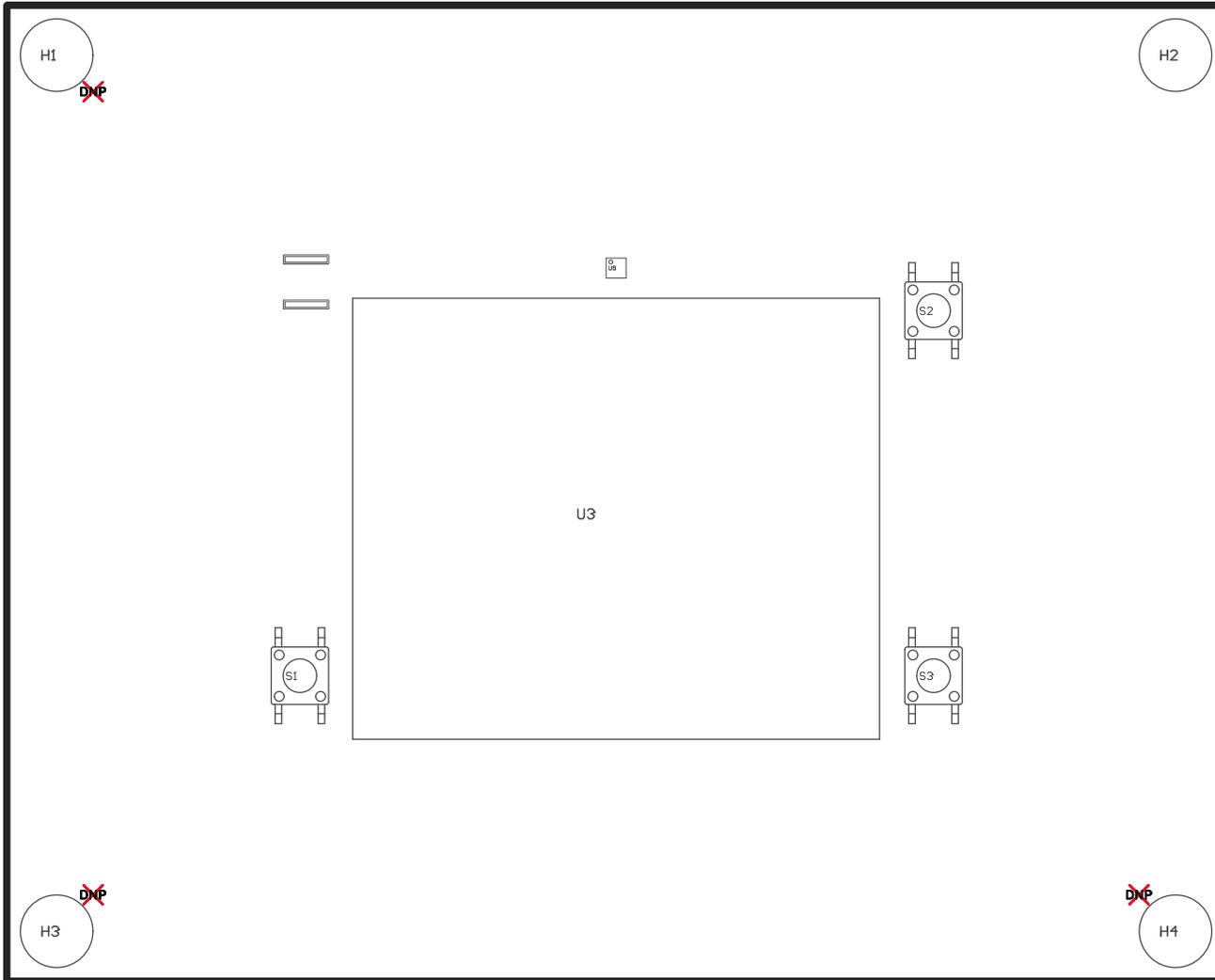


- ZZ1 ~~DNP~~ These assemblies are ESD sensitive, ESD precautions shall be observed.
- ZZ2 ~~DNP~~ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ3 ~~DNP~~ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- ZZ4 ~~DNP~~ Place SH-J1 on J1 and SH-J2 on J3 (pins 1 -2) and SH-J3 to SH-J4 on J7, SH-J3 (pins 1-2)
- ZZ5 ~~DNP~~ Component BL1 must be assembled to U3 Before U3 is attached to the board.
- ZZ6 ~~DNP~~ Remove protective coverings from BL1 and U3
- ZZ7 ~~DNP~~ Slide pins of U3 into holes of BL1. BL1 must lie flat on the back of U3
- ZZ8 ~~DNP~~ Solder U3 - BL1 assembly to the board.
- ZZ9 ~~DNP~~ Solder Pins 1, 2, 3, 18, 19, and 20 of U3 to BL1 from the top to insure electrical continuity.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: ISE4024	REV: E2	SUN REV: Not In VersionControl
	TIDA-00373		
PLOT NAME = Top Assembly Drawing	GENERATED : 2/10/2015	7:03:07 PM	TEXAS INSTRUMENTS



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